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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3e-4tn144c

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM ¹	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

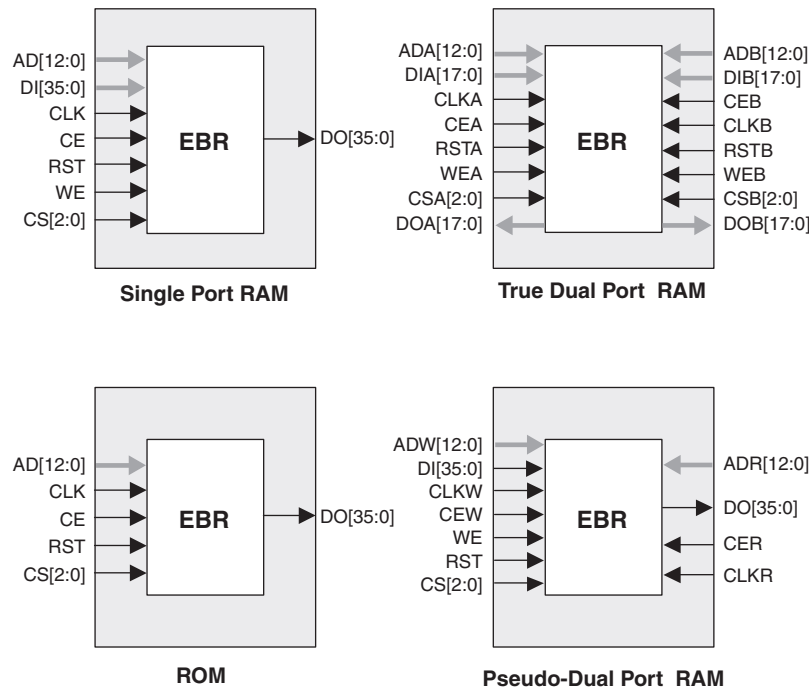
The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-14. sysMEM Memory Primitives

The EBR memory supports three forms of write behavior for single port or dual port operation:

1. **Normal** – data on the output appears only during read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port during a write cycle. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old content of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-15.

Figure 2-26. DQS Local Bus

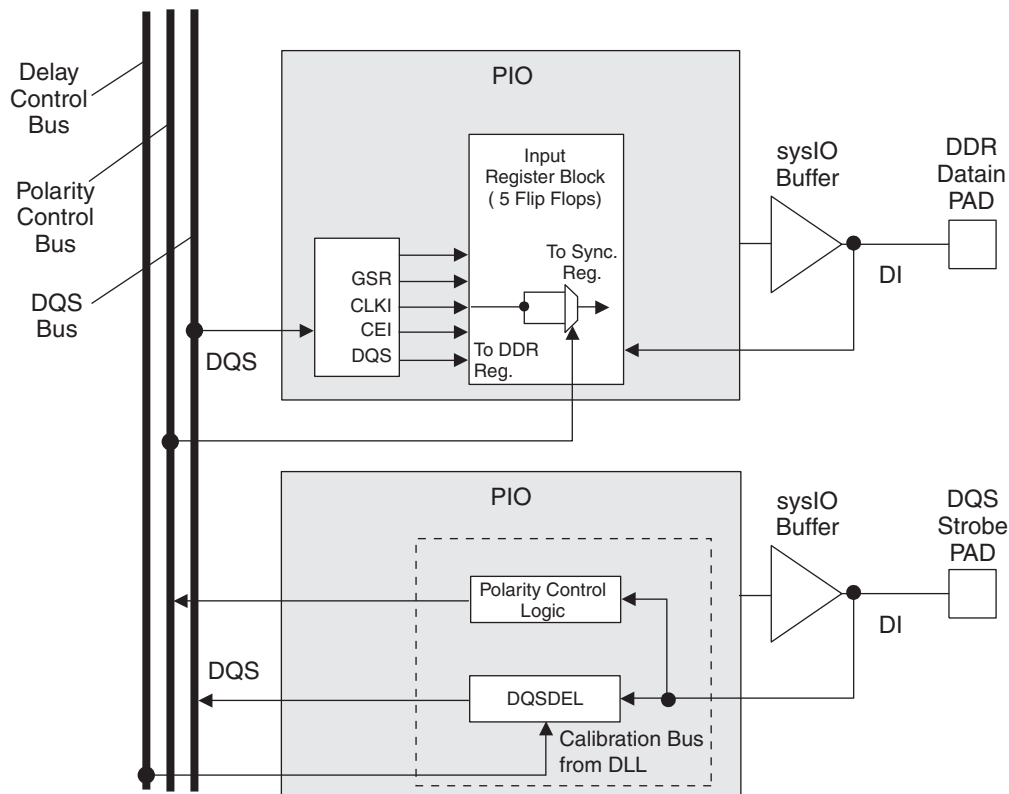


Figure 2-27. DLL Calibration Bus and DQS/DQS Transition Distribution

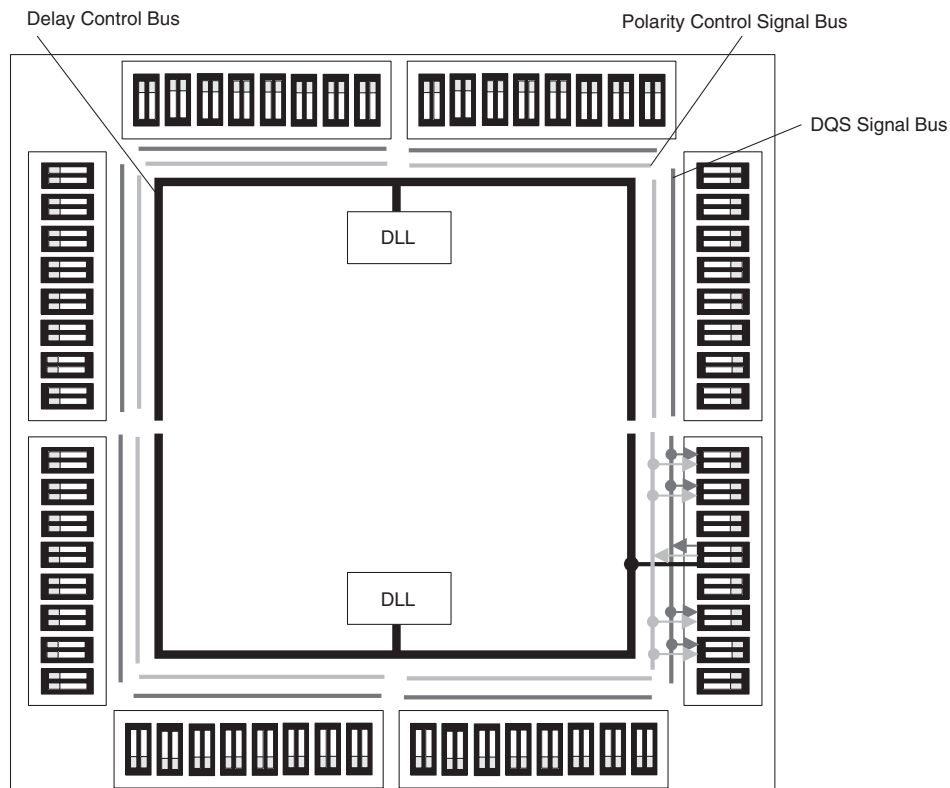


Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

Leave Alone I/O

When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

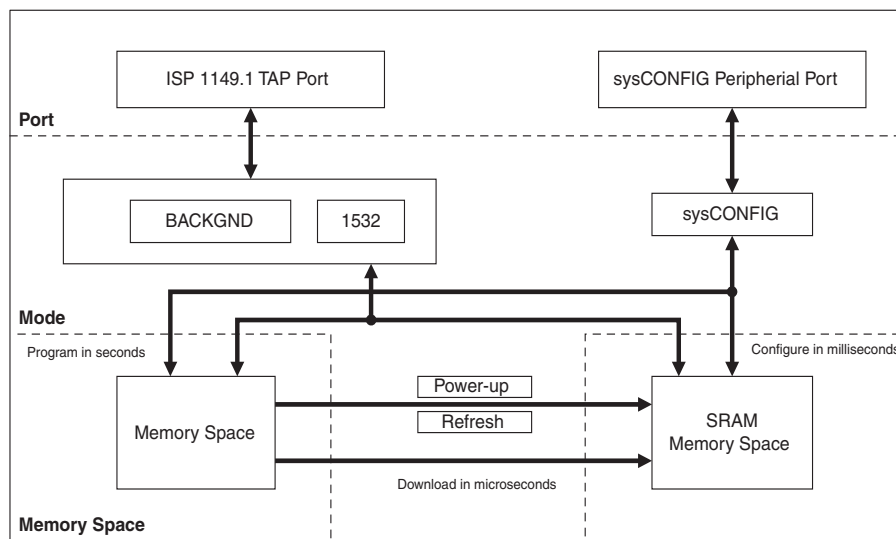
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology*, for details.

Security

The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

Absolute Maximum Ratings^{1, 2, 3, 4}

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied ⁵	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied ⁵	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to ($V_{IHMAX} + 2$) volts is permitted for a duration of <20ns.

Recommended Operating Conditions³

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX} ⁴	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO} ^{1, 2}	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ} ¹	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX} . For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC} .
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/ μ s during power up when transitioning between 0V and 3.3V.

Initialization Supply Current^{1, 2, 3, 4, 5, 6}**Over Recommended Operating Conditions**

Symbol	Parameter	Device	Typ. ⁷	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.

2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.

4. Frequency 0MHz.

5. Typical user pattern.

6. Assume normal bypass capacitor/decoupling capacitor across the supply.

7. $T_A=25^{\circ}C$, power supplies at nominal voltage.

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeXP devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

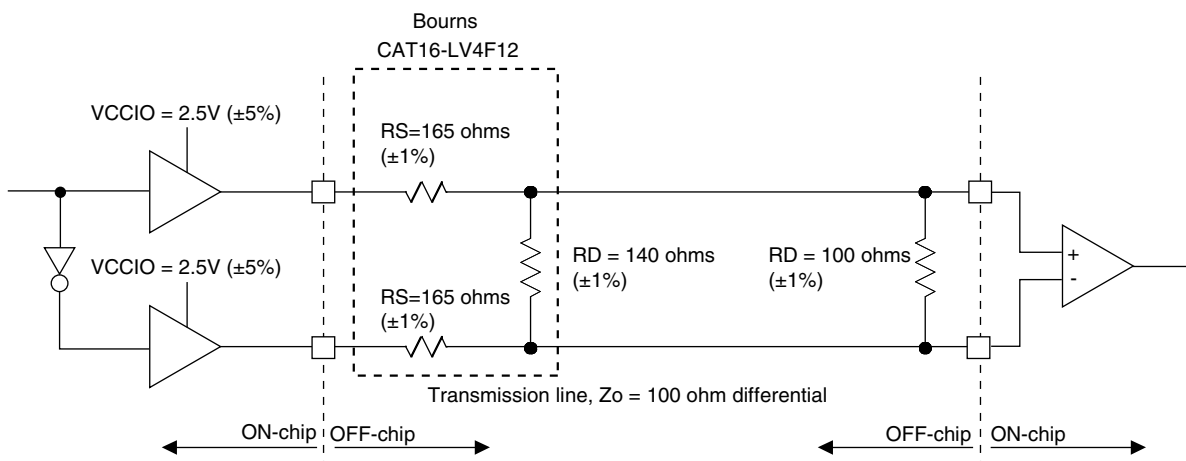


Table 3-1. LVDS25E DC Conditions

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	ohms
I_{DC}	DC output current	3.66	mA

BLVDS

The LatticeXP devices support BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

LatticeXP Internal Timing Parameters¹ (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t _{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t _{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.
Timing v.F0.11

LatticeXP Family Timing Adders¹ (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.8	0.8	0.8	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.5	0.5	0.5	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.3	0.3	0.3	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.4	0.4	0.4	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.3	0.3	0.3	ns
LVC MOS33_2mA	LVC MOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVC MOS25_2mA	LVC MOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVC MOS18_2mA	LVC MOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVC MOS15_2mA	LVC MOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVC MOS 2.5, 12mA.
Timing v.F0.11

Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTTL and LVCMOS Standards

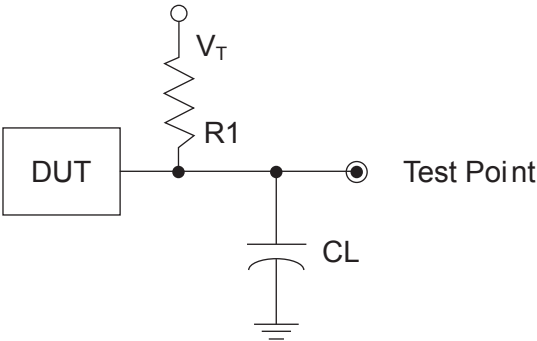


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	C _L	Timing Ref.	V _T
LVTTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = V _{CCIO} /2	—
			LVCMOS 1.8 = V _{CCIO} /2	—
			LVCMOS 1.5 = V _{CCIO} /2	—
			LVCMOS 1.2 = V _{CCIO} /2	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	V _{CCIO} /2	V _{OL}
LVCMOS 2.5 I/O (Z -> L)			V _{CCIO} /2	V _{OH}
LVCMOS 2.5 I/O (H -> Z)			V _{OH} - 0.15	V _{OL}
LVCMOS 2.5 I/O (L -> Z)			V _{OL} + 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration, the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal. (Active low). Any I/O pin can be configured to be GSRN.
NC	—	No connect.
GND	—	GND - Ground. Dedicated Pins.
V _{CC}	—	V _{CC} - The power supply pins for core logic. Dedicated Pins.
V _{CCAUX}	—	V _{CCAUX} - The Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated Pins.
V _{CCP0}	—	Voltage supply pins for ULM0PLL (and LLM1PLL ¹).
V _{CCP1}	—	Voltage supply pins for URM0PLL (and LRM1PLL ¹).
GNDP0	—	Ground pins for ULM0PLL (and LLM1PLL ¹).
GNDP1	—	Ground pins for URM0PLL (and LRM1PLL ¹).
V _{CCIOx}	—	V _{CCIO} - The power supply pins for I/O bank x. Dedicated Pins.
V _{REF1(x)} , V _{REF2(x)}	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V _{REF} inputs. When not used, they may be used as I/O pins.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	—	Reference clock (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
[LOC][num]_PLL[T, C]_FB_A	—	Optional feedback (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
PCLK[T, C]_[n:0]_[3:0]	—	Primary Clock Pads, T = true and C = complement, n per side, indexed by bank and 0, 1, 2, 3 within bank.
[LOC]DQS[num]	—	DQS input Pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = Ball function number. Any pad can be configured to be DQS output.

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
44	GNDIO4	4	-	-
45	PB15A	4	T	PCLKT4_0
46	PB15B	4	C	PCLKC4_0
47	VCCIO4	4	-	-
48	PB19A	4	T	DQS
49	PB19B	4	C	VREF1_4
50	PB24A	4	-	VREF2_4
51	PR18B	3	C ³	-
52	GNDIO3	3	-	-
53	PR18A	3	T ³	-
54	PR15B	3	-	VREF1_3
55	PR14A	3	-	VREF2_3
56	PR13B	3	C	-
57	PR13A	3	T	-
58	VCCIO3	3	-	-
59	GNDP1	-	-	-
60	VCCP1	-	-	-
61	PR9B	2	C	PCLKC2_0
62	PR9A	2	T	PCLKT2_0
63	PR8B	2	C	RUM0_PLLC_IN_A
64	PR8A	2	T	RUM0_PLLT_IN_A
65	VCCIO2	2	-	-
66	PR6B	2	-	VREF1_2
67	PR5A	2	-	VREF2_2
68	GNDIO2	2	-	-
69	PR3B	2	C	RUM0_PLLC_FB_A
70	PR3A	2	T	RUM0_PLLT_FB_A
71	VCCAUX	-	-	-
72	TDO	-	-	-
73	VCCJ	-	-	-
74	TDI	-	-	-
75	TMS	-	-	-
76	TCK	-	-	-
77	VCC	-	-	-
78	PT24A	1	-	-
79	PT23A	1	-	D0
80	PT22B	1	-	D1
81	PT21A	1	-	D2
82	VCCIO1	1	-	-
83	PT20B	1	-	D3
84	GNDIO1	1	-	-
85	PT17A	1	-	D4
86	PT16A	1	-	D5
87	PT15B	1	-	D6

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP "C" only.

2. Applies to LFXP "E" only.

3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T ³	DQS	PL41A	6	T ³	DQS
P2	PL37B	6	C ³	-	PL41B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T ³	-	PL43A	6	T ³	-
N3	PL39B	6	C ³	-	PL43B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN ¹ /TOE ²	-	-	-	SLEEPN ¹ /TOE ²	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
K11	GND	-	-	-	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-	GND	-	-	-
R10	GND	-	-	-	GND	-	-	-	GND	-	-	-
R11	GND	-	-	-	GND	-	-	-	GND	-	-	-
R12	GND	-	-	-	GND	-	-	-	GND	-	-	-
R13	GND	-	-	-	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-	GND	-	-	-
H9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
R9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
F5	PROGRAMN	7	-	-	PROGRAMN	7	-	-
E3	CCLK	7	-	-	CCLK	7	-	-
C1	PL2B	7	-	-	PL2B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G5	PL3A	7	T ³	-	PL3A	7	T ³	-
G6	PL3B	7	C ³	-	PL3B	7	C ³	-
F4	PL4A	7	T	-	PL4A	7	T	-
F3	PL4B	7	C	-	PL4B	7	C	-
G4	PL5A	7	T ³	-	PL5A	7	T ³	-
G3	PL5B	7	C ³	-	PL5B	7	C ³	-
D1	PL6A	7	T ³	-	PL6A	7	T ³	-
D2	PL6B	7	C ³	-	PL6B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E2	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
H5	PL8A	7	T ³	-	PL8A	7	T ³	-
H6	PL8B	7	C ³	-	PL8B	7	C ³	-
H4	PL9A	7	-	-	PL9A	7	-	-
H3	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
F1	PL11A	7	T ³	DQS	PL11A	7	T ³	DQS
F2	PL11B	7	C ³	-	PL11B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J5	PL12A	7	T	-	PL12A	7	T	-
J6	PL12B	7	C	-	PL12B	7	C	-
G1	PL13A	7	T ³	-	PL13A	7	T ³	-
G2	PL13B	7	C ³	-	PL13B	7	C ³	-
J4	PL15A	7	T ³	-	PL15A	7	T ³	-
J3	PL15B	7	C ³	-	PL15B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
H1	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H2	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL17A	7	T ³	-	PL17A	7	T ³	-
J2	PL17B	7	C ³	-	PL17B	7	C ³	-
K3	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
K2	PL19B	7	-	-	PL19B	7	-	-
K4	PL20A	7	T ³	DQS	PL20A	7	T ³	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-
K5	PL20B	7	C ³	-	PL20B	7	C ³	-
K1	PL21A	7	T	-	PL21A	7	T	-
L2	PL21B	7	C	-	PL21B	7	C	-
L4	PL22A	7	T ³	-	PL22A	7	T ³	-
L3	PL22B	7	C ³	-	PL22B	7	C ³	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J21	PR20B	2	C ³	-	PR20B	2	C ³	-
J22	PR20A	2	T ³	DQS	PR20A	2	T ³	DQS
K18	PR19B	2	-	-	PR19B	2	-	-
K19	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
K21	PR17B	2	C ³	-	PR17B	2	C ³	-
K20	PR17A	2	T ³	-	PR17A	2	T ³	-
H21	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H22	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
J20	PR15B	2	C ³	-	PR15B	2	C ³	-
J19	PR15A	2	T ³	-	PR15A	2	T ³	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J17	PR13B	2	C ³	-	PR13B	2	C ³	-
J18	PR13A	2	T ³	-	PR13A	2	T ³	-
G21	PR12B	2	C	-	PR12B	2	C	-
G22	PR12A	2	T	-	PR12A	2	T	-
F21	PR11B	2	C ³	-	PR11B	2	C ³	-
F22	PR11A	2	T ³	DQS	PR11A	2	T ³	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-
H20	PR10B	2	-	-	PR10B	2	-	-
H19	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
H17	PR8B	2	C ³	-	PR8B	2	C ³	-
H18	PR8A	2	T ³	-	PR8A	2	T ³	-
E21	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E22	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D21	PR6B	2	C ³	-	PR6B	2	C ³	-
D22	PR6A	2	T ³	-	PR6A	2	T ³	-
G20	PR5B	2	C ³	-	PR5B	2	C ³	-
G19	PR5A	2	T ³	-	PR5A	2	T ³	-
G17	PR4B	2	C	-	PR4B	2	C	-
G18	PR4A	2	T	-	PR4A	2	T	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F18	PR3B	2	C ³	-	PR3B	2	C ³	-
F19	PR3A	2	T ³	-	PR3A	2	T ³	-
C22	PR2B	2	-	-	PR2B	2	-	-
F20	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-
D19	TDI	-	-	-	TDI	-	-	-
E19	TMS	-	-	-	TMS	-	-	-
D20	TCK	-	-	-	TCK	-	-	-
C20	-	-	-	-	PT56A	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4F484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5F484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3F388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4F388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5F388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3F256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4F256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5F256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4Q208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3T100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4T100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3Q208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4Q208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4F388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
	02.0	DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
		Ordering Information	Updated Logic Signal Connections Dual Function column.
			Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
September 2005	03.0	Architecture	Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
			Added clarification of PCI clamp.
		DC and Switching Characteristics	Added clarification to SLEEPN Pin Characteristics section.
			DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.